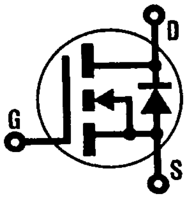
11E D ▌ 4855452 0008498 7 ▌
INTERNATIONAL RECTIFIER
Data Sheet No. PD-9.476A
T-39-11

INTERNATIONAL RECTIFIER IOR

HEXFET® TRANSISTORS

IRF634
IRF635



N-CHANNEL

TO-220

250 Volt, 0.45 Ohm HEXFET
TO-220AB Plastic Package

The HEXFET® technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry and unique processing of the HEXFET design achieve very low on-state resistance combined with high transconductance and great device ruggedness.

The HEXFET transistors also feature all of the well established advantages of MOSFETs such as voltage control, very fast switching, ease of paralleling, and temperature stability of the electrical parameters.

They are well suited for applications such as motor controls, inverters, choppers and audio amplifiers. The voltage rating makes them cost effective for the 115 volt offline switching applications like battery chargers, hand drills, lighting ballasts, washing machines and dryers.

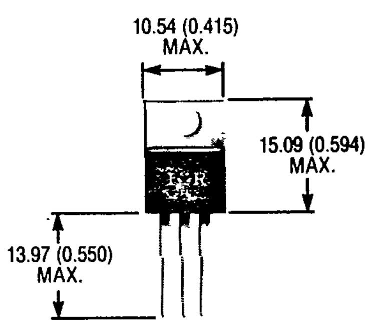
Features

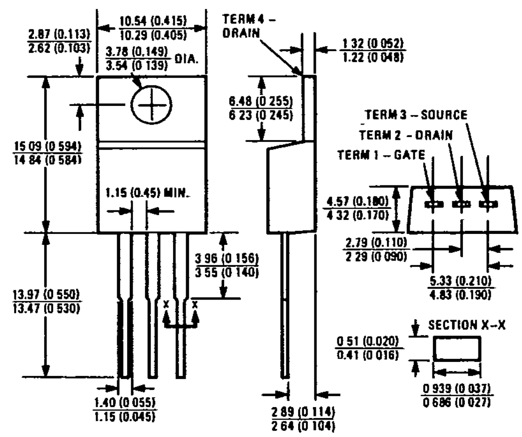
- Compact Plastic Package
- Fast Switching
- Low Drive Current
- Ease of Paralleling
- Excellent Temperature Stability

Product Summary

Part Number	V_{DS}	$R_{DS(on)}$	I_D
IRF634	250V	0.45	8.1
IRF635	250V	0.68	6.5

CASE STYLE AND DIMENSIONS





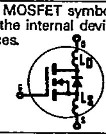
Case Style TO-220AB
Dimensions in Millimeters and (Inches)

IRF634, IRF635 Devices

Absolute Maximum Ratings

Parameter		IRF634	IRF635	Units
V_{DS}	Drain - Source Voltage ①	250	250	V
V_{DGR}	Drain - Gate Voltage (R_{GS} = 20 KΩ) ①	250	250	V
I_D @ T_C = 25°C	Continuous Drain Current	8.1	6.5	A
I_D @ T_C = 100°C	Continuous Drain Current	5.1	4.1	A
I_{DM}	Pulsed Drain Current ②	32	26	A
V_{GS}	Gate — Source Voltage	±20		V
P_D @ T_C = 25°C	Max. Power Dissipation	75		W
	Linear Derating Factor	0.60		W/K⑤
I_{LM}	Inductive Current, Clamped	(See Fig. 14) L = 100 μH 32	26	A
I_L	Unclamped Inductive Current (Avalanche Current) ③	(See Fig. 15) 3.1		A
T_J T_{stg}	Operating Junction and Storage Temperature Range	−55 to 150		°C
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10s)		°C

Electrical Characteristics @ T_C = 25°C (Unless Otherwise Specified)

Parameter		Type	Min.	Typ.	Max.	Units	Test Conditions	
BV_{DSS}	Drain - Source Breakdown Voltage	IRF634	250	—	—	V	V_{GS} = 0V	
		IRF635	250	—	—	V	I_D = 250 μA	
$V_{GS(th)}$	Gate Threshold Voltage	ALL	2.0	—	4.0	V	V_{DS} = V_{GS}, I_D = 250 μA	
I_{GSS}	Gate-Source Leakage Forward	ALL	—	—	500	nA	V_{GS} = 20V	
I_{GSS}	Gate-Source Leakage Reverse	ALL	—	—	−500	nA	V_{GS} = −20V	
I_{DSS}	Zero Gate Voltage Drain Current	ALL	—	—	250	μA	V_{DS} = Max. Rating, V_{GS} = 0V	
			—	—	1000	μA	V_{DS} = Max. Rating × 0.8, V_{GS} = 0V, T_C = 125°C	
$I_{D(on)}$	On-State Drain Current ④	IRF634	8.1	—	—	A	V_{DS} > $I_{D(on)}$ × $R_{DS(on)max.}$, V_{GS} = 10V	
		IRF635	6.5	—	—	A		
$R_{DS(on)}$	Static Drain-Source On-State Resistance ④	IRF634	—	0.40	0.45	Ω	V_{GS} = 10V, I_D = 4.1A	
		IRF635	—	0.45	0.68	Ω		
g_{fs}	Forward Transconductance ④	ALL	2.9	4.3	—	S(Ʊ)	V_{DS} = 2×V_{GS}, I_{DS} = 4.1A	
C_{iss}	Input Capacitance	ALL	—	600	—	pF	V_{GS} = 0V, V_{DS} = 25V, f = 1.0 MHz See Fig. 10	
C_{oss}	Output Capacitance	ALL	—	180	—	pF		
C_{rss}	Reverse Transfer Capacitance	ALL	—	52	—	pF		
$t_{d(on)}$	Turn-On Delay Time	ALL	—	9.1	14	ns	V_{DD} = 125V, I_D ≈ 8.1A, R_G = 12Ω, R_D = 15Ω See Fig. 16 (MOSFET switching times are essentially independent of operating temperature.)	
t_r	Rise Time	ALL	—	23	35	ns		
$t_{d(off)}$	Turn-Off Delay Time	ALL	—	31	47	ns		
t_f	Fall Time	ALL	—	19	29	ns		
Q_g	Total Gate Charge (Gate-Source Plus Gate-Drain)	ALL	—	24	35	nC	V_{GS} = 10V, I_D = 8.1A, V_{DS} = 0.8 Max. Rating. See Fig. 17 for test circuit. (Gate charge is essentially independent of operating temperature.)	
Q_{gs}	Gate-Source Charge	ALL	—	5.1	7.7	nC		
Q_{gd}	Gate-Drain ("Miller") Charge	ALL	—	12	18	nC		
L_D	Internal Drain Inductance	ALL	—	4.5	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die.	Modified MOSFET symbol showing the internal device inductances. 
L_S	Internal Source Inductance	ALL	—	7.5	—	nH	Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.	

Thermal Resistance

R_{thJC}	Junction-to-Case	ALL	—	—	1.67	K/W⑤	
R_{thCS}	Case-to-Sink	ALL	—	0.50	—	K/W⑤	Mounting surface flat, smooth, and greased.
R_{thJA}	Junction-to-Ambient	ALL	—	—	80	K/W⑤	Typical socket mount

Source-Drain Diode Ratings and Characteristics

I_S	Continuous Source Current (Body Diode)	IRF634	—	—	8.1	A	Modified MOSFET symbol showing the integral reverse P-N junction rectifier.
		IRF635	—	—	6.5	A	
I_{SM}	Pulse Source Current (Body Diode) ③	IRF634	—	—	32	A	
		IRF635	—	—	26	A	
V_{SD}	Diode Forward Voltage ②	ALL	—	—	2.0	V	T_C = 25°C, I_S = 8.1A, V_{GS} = 0V
t_{rr}	Reverse Recovery Time	ALL	92	190	390	ns	T_J = 25°C, I_F = 8.1A, dI_F/dt = 100 A/μs
Q_{RR}	Reverse Recovered Charge	ALL	0.63	1.3	2.7	μC	T_J = 25°C, I_F = 8.1A, dI_F/dt = 100A/μs
t_{on}	Forward Turn-on Time	ALL	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				

① T_J = 25°C to 150°C
② Repetitive Rating: Pulse width limited by max. junction temperature. See transient Thermal Response Curve (Fig. 5)
③ V_{dd} = 25V, T_j = 25°C, L = 100 μH R_G = 25Ω
④ Pulse Test: Pulse width ≤ 300 μs Duty Cycle ≤ 2%.
⑤ K/W = °C/W, W/K = W/°C

TO-220

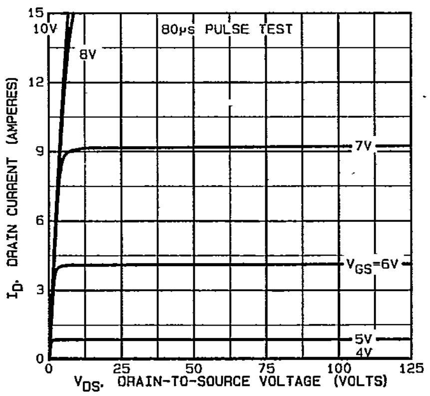


Fig. 1 — Typical Output Characteristics

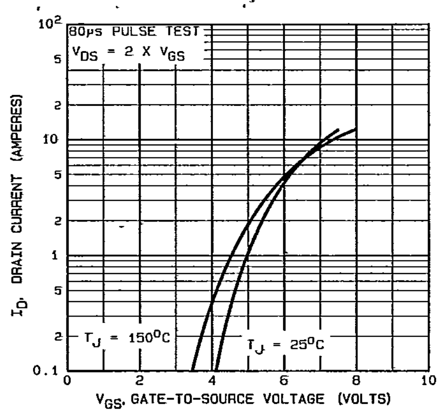


Fig. 2 — Typical Transfer Characteristics

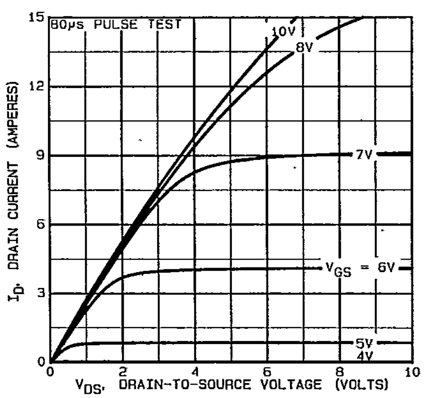


Fig. 3 — Typical Saturation Characteristics

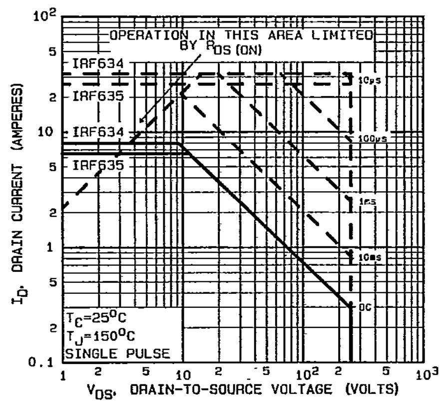


Fig. 4 — Maximum Safe Operating Area

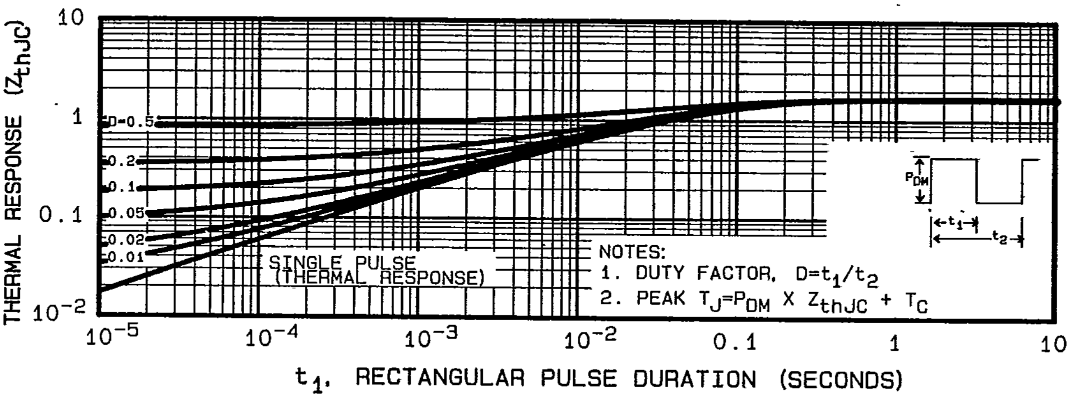


Fig. 5 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

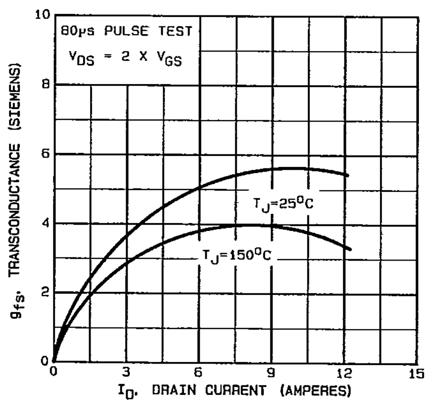


Fig. 6 — Typical Transconductance Vs. Drain Current

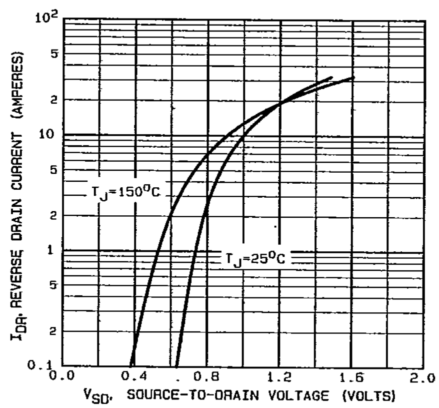


Fig. 7 — Typical Source-Drain Diode Forward Voltage

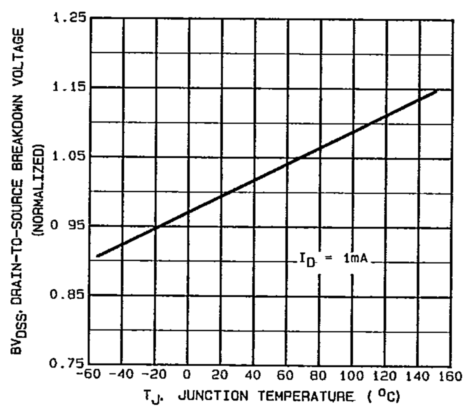


Fig. 8 — Breakdown Voltage Vs. Temperature

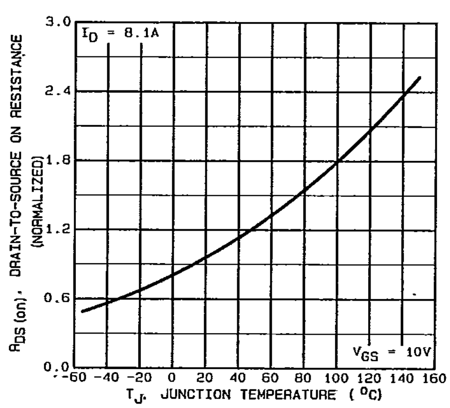


Fig. 9 — Normalized On-Resistance Vs. Temperature

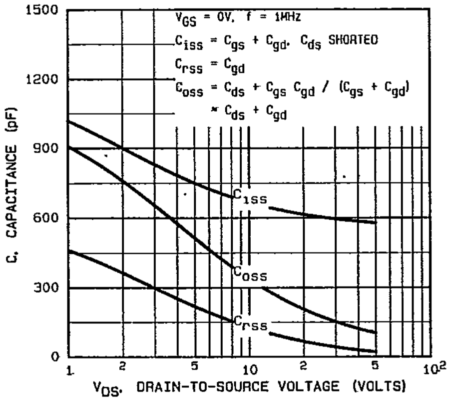


Fig. 10 — Typical Capacitance Vs. Drain-to-Source Voltage

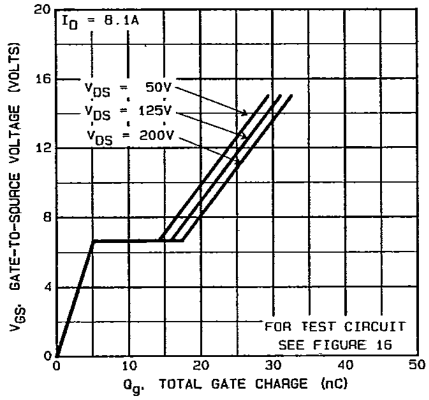


Fig. 11 — Typical Gate Charge Vs. Gate-to-Source Voltage

TO-220

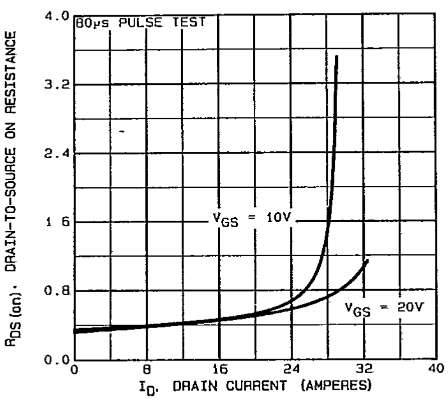


Fig. 12 — Typical On-Resistance Vs. Drain Current

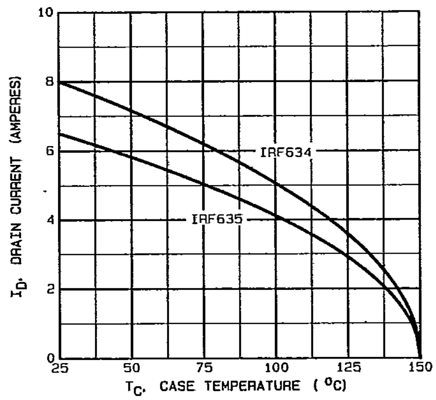


Fig. 13 — Maximum Drain Current Vs. Case Temperature

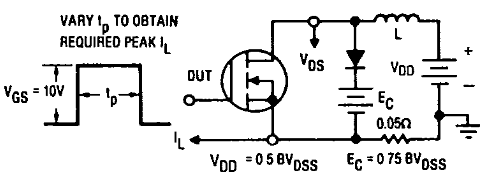


Fig. 14a — Clamped Inductive Test Circuit

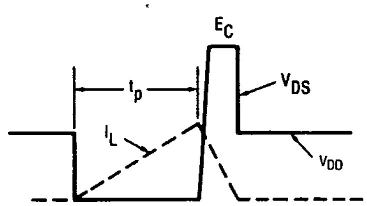


Fig. 14b — Clamped Inductive Waveforms

IRF634, IRF635 Devices

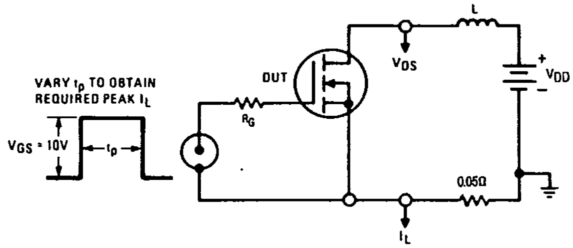


Fig. 15a — Unclamped Inductive Test Circuit

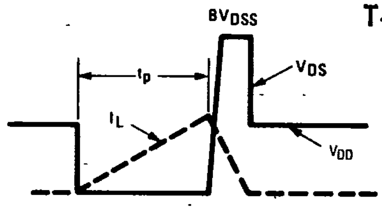


Fig. 15b — Unclamped Inductive Load Test Waveforms

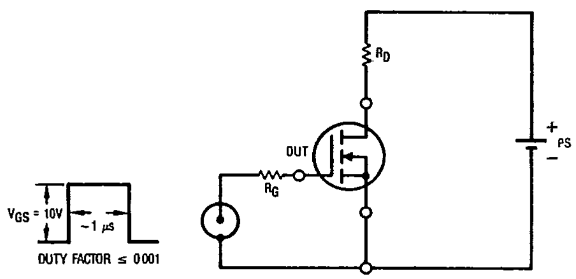


Fig. 16 — Switching Time Test Circuit

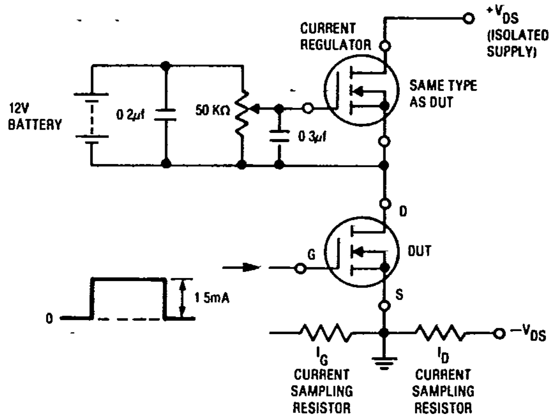


Fig. 17 — Gate Charge Test Circuit

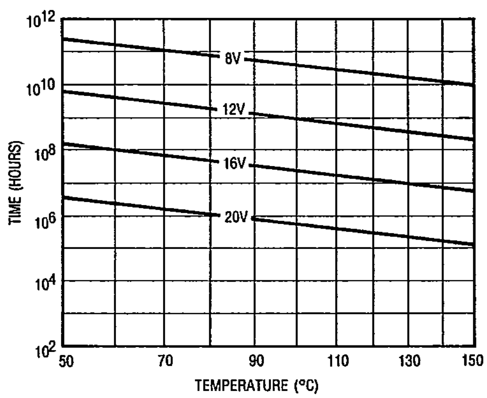


*Fig. 18 — Typical Time to Accumulated 1% Gate Failure

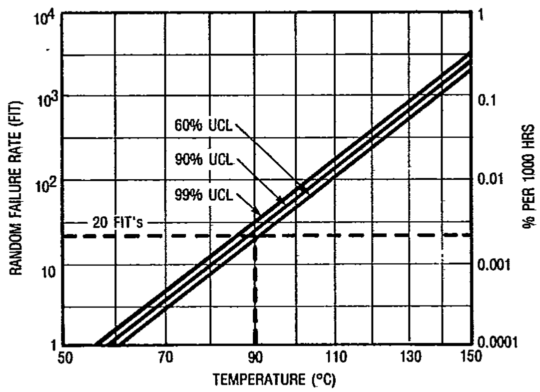


*Fig. 19 — Typical High Temperature Reverse Bias (HTRB) Failure Rate

*The data shown is correct as of April 15, 1987. This information is updated on a quarterly basis; for the latest reliability data, please contact your local IR field office.